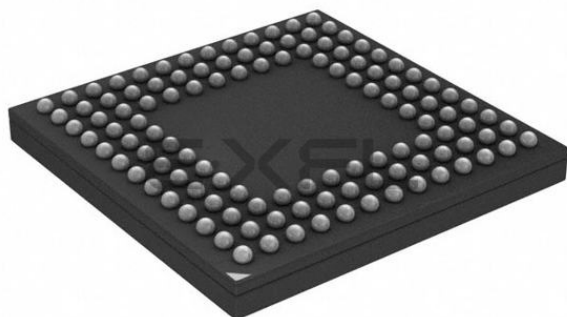




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Details

Product Status	Discontinued at Digi-Key
Core Processor	ARM® Cortex®-M3
Core Size	32-Bit Single-Core
Speed	48MHz
Connectivity	EBI/EMI, I ² C, IrDA, SmartCard, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, LCD, POR, PWM, WDT
Number of I/O	93
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	1.98V ~ 3.8V
Data Converters	A/D 8x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	120-VFBGA
Supplier Device Package	120-BGA (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/efm32lg895f128g-e-bga120r

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3.2.7 EFM32LG332

The features of the EFM32LG332 is a subset of the feature set described in the EFM32LG Reference Manual. The following table describes device specific implementation of the features.

Table 3.7. EFM32LG332 Configuration Summary

Module	Configuration	Pin Connections
Cortex-M3	Full configuration	NA
DBG	Full configuration	DBG_SWCLK, DBG_SWDIO, DBG_SWO
MSC	Full configuration	NA
DMA	Full configuration	NA
RMU	Full configuration	NA
EMU	Full configuration	NA
CMU	Full configuration	CMU_OUT0, CMU_OUT1
WDOG	Full configuration	NA
PRS	Full configuration	NA
USB	Full configuration	USB_VBUS, USB_VBUSEN, USB_VREGI, USB_VREGO, USB_DM, USB_DMPU, USB_DP, USB_ID
I2C0	Full configuration	I2C0_SDA, I2C0_SCL
I2C1	Full configuration	I2C1_SDA, I2C1_SCL
USART0	Full configuration with IrDA	US0_TX, US0_RX, US0_CLK, US0_CS
USART1	Full configuration with I2S	US1_TX, US1_RX, US1_CLK, US1_CS
USART2	Full configuration with I2S	US2_TX, US2_RX, US2_CLK, US2_CS
LEUART0	Full configuration	LEU0_TX, LEU0_RX
LEUART1	Full configuration	LEU1_TX, LEU1_RX
TIMER0	Full configuration with DTI	TIM0_CC[2:0], TIM0_CDTI[2:0]
TIMER1	Full configuration	TIM1_CC[2:0]
TIMER2	Full configuration	TIM2_CC[2:0]
TIMER3	Full configuration	TIM3_CC[2:0]
RTC	Full configuration	NA
BURTC	Full configuration	NA
LETIMER0	Full configuration	LET0_O[1:0]
PCNT0	Full configuration, 16-bit count register	PCNT0_S[1:0]
PCNT1	Full configuration, 8-bit count register	PCNT1_S[1:0]
PCNT2	Full configuration, 8-bit count register	PCNT2_S[1:0]
ACMP0	Full configuration	ACMP0_CH[3:0], ACMP0_O
ACMP1	Full configuration	ACMP1_CH[0], ACMP1_O
VCMP	Full configuration	NA
ADC0	Full configuration	ADC0_CH[7:0]
DAC0	Full configuration	DAC0_OUT[1:0], DAC0_OUTxALT

Module	Configuration	Pin Connections
PCNT2	Full configuration, 8-bit count register	PCNT2_S[1:0]
ACMP0	Full configuration	ACMP0_CH[7:0], ACMP0_O
ACMP1	Full configuration	ACMP1_CH[7:0], ACMP1_O
VCMP	Full configuration	NA
ADC0	Full configuration	ADC0_CH[7:0]
DAC0	Full configuration	DAC0_OUT[1:0], DAC0_OUTxALT
OPAMP	Full configuration	Outputs: OPAMP_OUTx, OPAMP_OUTxALT, Inputs: OPAMP_Px, OPAMP_Nx
AES	Full configuration	NA
GPIO	86 pins	Available pins are shown in 5.10.3 GPIO Pinout Overview

Module	Configuration	Pin Connections
AES	Full configuration	NA
GPIO	56 pins	Available pins are shown in 5.12.3 GPIO Pinout Overview
LCD	Full configuration	LCD_SEG[19:0], LCD_COM[7:0], LCD_BCAP_P, LCD_BCAP_N, LCD_BEXT

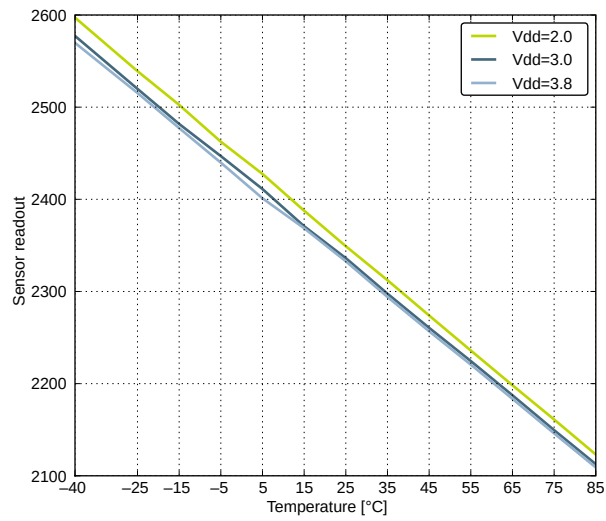


Figure 4.30. ADC Temperature Sensor Readout

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Spurious-Free Dynamic Range(SFDR)	SFDR _{DAC}	500 kSamples/s, 12 bit, single ended, internal 1.25V reference	—	62	—	dBc
		500 kSamples/s, 12 bit, single ended, internal 2.5V reference	—	56	—	dBc
		500 kSamples/s, 12 bit, differential, internal 1.25V reference	—	61	—	dBc
		500 kSamples/s, 12 bit, differential, internal 2.5V reference	—	55	—	dBc
		500 kSamples/s, 12 bit, differential, V _{DD} reference	—	60	—	dBc
Offset voltage, all packages except CSP	V _{DACOFF-SET}	After calibration, single ended	—	2	9	mV
		After calibration, differential	—	2	—	mV
Offset voltage, CSP devices	V _{DACOFF-SET}	After calibration, single ended	—	2	—	mV
		After calibration, differential	—	2	—	mV
Differential non-linearity	DNL _{DAC}		—	±1	—	LSB
Integral non-linearity	INL _{DAC}		—	±5	—	LSB
No missing codes	MC _{DAC}		—	12	—	bits
VREF output voltage	V _{REF}	1.25 V reference	1.2	1.25	1.3	V
		2.5 V reference	2.4	2.5	2.6	V
VREF voltage drift	V _{REF_VDRIFT}	1.25 V reference	-12.4	2.3	18.2	mV/V
		2.5 V reference, VDD > 2.5 V	-24.6	5.3	35.2	mV/V
VREF temperature drift	V _{REF_TDRIFT}	1.25 V reference	-132	242	677	μV/°C
		2.5 V reference	-231	507	1271	μV/°C
VREF current consumption	I _{VREF}	1.25 V reference	—	67	97	μA
		2.5 V reference	—	55	72	μA
ADC and DAC VREF matching	V _{REF_MATCH}	1.25 V reference	—	99.85	—	%
		2.5 V reference	—	100.01	—	%

Note:

1. Measured with a static input code and no loading on the output. Includes required contribution from the voltage reference.

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
EBI_WEn	PF4	PF8	PF4					External Bus Interface (EBI) Write Enable output.
ETM_TCLK	PD7	PF8	PC6	PA6				Embedded Trace Module ETM clock .
ETM_TD0	PD6	PF9	PC7	PA2				Embedded Trace Module ETM data 0.
ETM_TD1	PD3	PD13	PD3	PA3				Embedded Trace Module ETM data 1.
ETM_TD2	PD4	PB15	PD4	PA4				Embedded Trace Module ETM data 2.
ETM_TD3	PD5	PF3	PD5	PA5				Embedded Trace Module ETM data 3.
GPIO_EM4WU0	PA0							Pin can be used to wake the system up from EM4
GPIO_EM4WU1	PA6							Pin can be used to wake the system up from EM4
GPIO_EM4WU2	PC9							Pin can be used to wake the system up from EM4
GPIO_EM4WU3	PF1							Pin can be used to wake the system up from EM4
GPIO_EM4WU4	PF2							Pin can be used to wake the system up from EM4
GPIO_EM4WU5	PE13							Pin can be used to wake the system up from EM4
HFX TAL_N	PB14							High Frequency Crystal negative pin. Also used as external optional clock input pin.
HFX TAL_P	PB13							High Frequency Crystal positive pin.
I2C0_SCL	PA1	PD7	PC7	PD15	PC1	PF1	PE13	I2C0 Serial Clock Line input / output.
I2C0_SDA	PA0	PD6	PC6	PD14	PC0	PF0	PE12	I2C0 Serial Data input / output.
I2C1_SCL	PC5	PB12	PE1					I2C1 Serial Clock Line input / output.
I2C1_SDA	PC4	PB11	PE0					I2C1 Serial Data input / output.
LES_ALTEX0	PD6							LESENSE alternate exite output 0.
LES_ALTEX1	PD7							LESENSE alternate exite output 1.
LES_ALTEX2	PA3							LESENSE alternate exite output 2.
LES_ALTEX3	PA4							LESENSE alternate exite output 3.
LES_ALTEX4	PA5							LESENSE alternate exite output 4.
LES_ALTEX5	PE11							LESENSE alternate exite output 5.
LES_ALTEX6	PE12							LESENSE alternate exite output 6.
LES_ALTEX7	PE13							LESENSE alternate exite output 7.
LES_CH0	PC0							LESENSE channel 0.
LES_CH1	PC1							LESENSE channel 1.
LES_CH2	PC2							LESENSE channel 2.
LES_CH3	PC3							LESENSE channel 3.
LES_CH4	PC4							LESENSE channel 4.
LES_CH5	PC5							LESENSE channel 5.
LES_CH6	PC6							LESENSE channel 6.
LES_CH7	PC7							LESENSE channel 7.
LES_CH8	PC8							LESENSE channel 8.

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
CMU_CLK0	PA2		PD7					Clock Management Unit, clock output number 0.
CMU_CLK1	PA1	PD8	PE12					Clock Management Unit, clock output number 1.
OPAMP_N0	PC5							Operational Amplifier 0 external negative input.
OPAMP_N1	PD7							Operational Amplifier 1 external negative input.
OPAMP_N2	PD3							Operational Amplifier 2 external negative input.
DAC0_OUT0 / OPAMP_OUT0	PB11							Digital to Analog Converter DAC0_OUT0 /OPAMP output channel number 0.
DAC0_OUT0ALT / OPAMP_OUT0A LT	PC0	PC1	PC2	PC3	PD0			Digital to Analog Converter DAC0_OUT0ALT / OPAMP alternative output for channel 0.
DAC0_OUT1 / OPAMP_OUT1	PB12							
DAC0_OUT1ALT / OPAMP_OUT1A LT					PD1			Digital to Analog Converter DAC0_OUT1ALT / OPAMP alternative output for channel 1.
OPAMP_OUT2	PD5	PD0						Operational Amplifier 2 output.
OPAMP_P0	PC4							Operational Amplifier 0 external positive input.
OPAMP_P1	PD6							Operational Amplifier 1 external positive input.
OPAMP_P2	PD4							Operational Amplifier 2 external positive input.
DBG_SWCLK	PF0	PF0	PF0	PF0				Debug-interface Serial Wire clock input. Note that this function is enabled to pin out of reset, and has a built-in pull down.
DBG_SWDIO	PF1	PF1	PF1	PF1				Debug-interface Serial Wire data input / output. Note that this function is enabled to pin out of reset, and has a built-in pull up.
DBG_SWO	PF2		PD1	PD2				Debug-interface Serial Wire viewer Output. Note that this function is not enabled after reset, and must be enabled by software to be used.
ETM_TCLK	PD7		PC6	PA6				Embedded Trace Module ETM clock .
ETM_TD0	PD6		PC7	PA2				Embedded Trace Module ETM data 0.
ETM_TD1	PD3		PD3	PA3				Embedded Trace Module ETM data 1.
ETM_TD2	PD4		PD4	PA4				Embedded Trace Module ETM data 2.
ETM_TD3	PD5		PD5	PA5				Embedded Trace Module ETM data 3.
GPIO_EM4WU0	PA0							Pin can be used to wake the system up from EM4
GPIO_EM4WU1	PA6							Pin can be used to wake the system up from EM4
GPIO_EM4WU2	PC9							Pin can be used to wake the system up from EM4
GPIO_EM4WU3	PF1							Pin can be used to wake the system up from EM4
GPIO_EM4WU4	PF2							Pin can be used to wake the system up from EM4
GPIO_EM4WU5	PE13							Pin can be used to wake the system up from EM4

5.7 EFM32LG332 (TQFP64)

5.7.1 Pinout

The EFM32LG332 pinout is shown in the following figure and table. Alternate locations are denoted by "#" followed by the location number (Multiple locations on the same pin are split with "/"). Alternate locations can be configured in the LOCATION bitfield in the *_ROUTE register in the module in question.

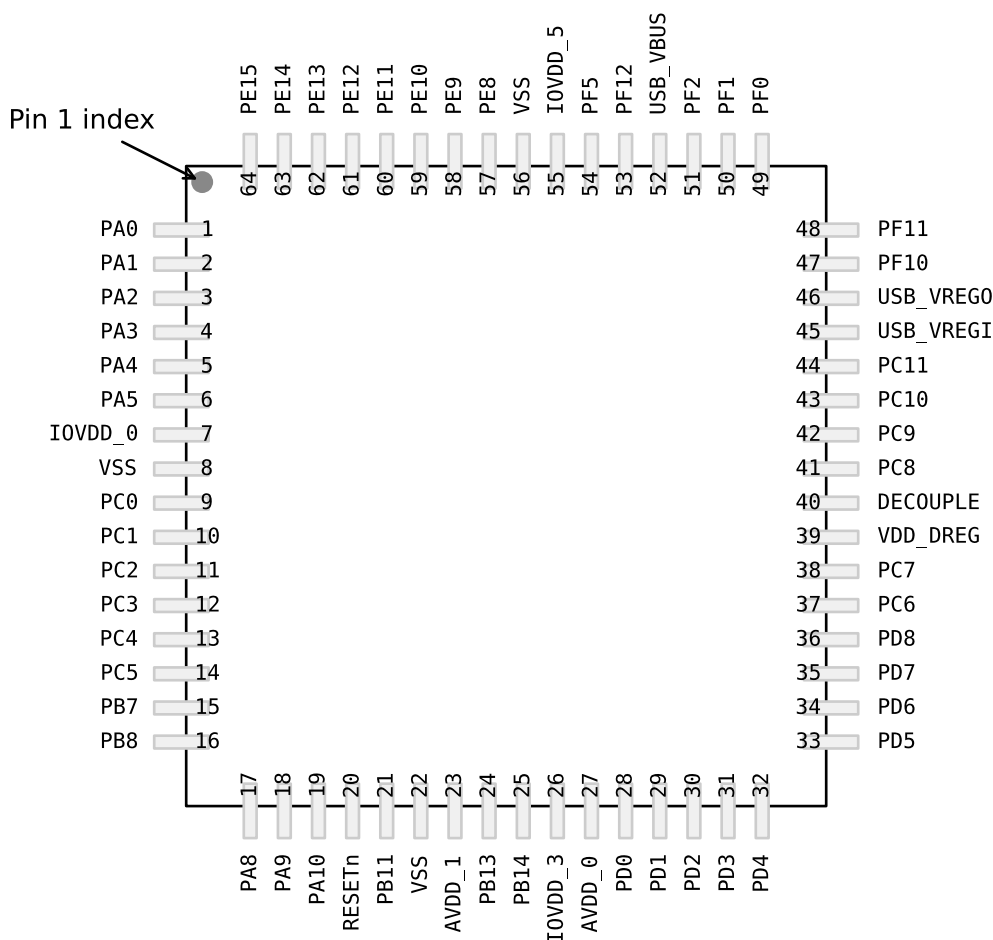


Figure 5.13. EFM32LG332 Pinout (top view, not to scale)

Table 5.19. Device Pinout

QFP64 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
1	PA0		TIM0_CC0 #0/1/4	LEU0_RX #4 I2C0_SDA #0	PRS_CH0 #0 GPIO_EM4WU0
2	PA1		TIM0_CC1 #0/1	I2C0_SCL #0	CMU_CLK1 #0 PRS_CH1 #0

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
CMU_CLK0	PA2		PD7					Clock Management Unit, clock output number 0.
CMU_CLK1	PA1	PD8	PE12					Clock Management Unit, clock output number 1.
OPAMP_N0	PC5							Operational Amplifier 0 external negative input.
OPAMP_N1	PD7							Operational Amplifier 1 external negative input.
OPAMP_N2	PD3							Operational Amplifier 2 external negative input.
DAC0_OUT0 / OPAMP_OUT0	PB11							Digital to Analog Converter DAC0_OUT0 /OPAMP output channel number 0.
DAC0_OUT0ALT / OPAMP_OUT0ALT	PC0	PC1	PC2	PC3	PD0			Digital to Analog Converter DAC0_OUT0ALT / OPAMP alternative output for channel 0.
DAC0_OUT1ALT / OPAMP_OUT1ALT					PD1			Digital to Analog Converter DAC0_OUT1ALT / OPAMP alternative output for channel 1.
OPAMP_OUT2	PD5	PD0						Operational Amplifier 2 output.
OPAMP_P0	PC4							Operational Amplifier 0 external positive input.
OPAMP_P1	PD6							Operational Amplifier 1 external positive input.
OPAMP_P2	PD4							Operational Amplifier 2 external positive input.
DBG_SWCLK	PF0	PF0	PF0	PF0				Debug-interface Serial Wire clock input. Note that this function is enabled to pin out of reset, and has a built-in pull down.
DBG_SWDIO	PF1	PF1	PF1	PF1				Debug-interface Serial Wire data input / output. Note that this function is enabled to pin out of reset, and has a built-in pull up.
DBG_SWO	PF2		PD1	PD2				Debug-interface Serial Wire viewer Output. Note that this function is not enabled after reset, and must be enabled by software to be used.
ETM_TCLK	PD7		PC6					Embedded Trace Module ETM clock .
ETM_TD0	PD6		PC7	PA2				Embedded Trace Module ETM data 0.
ETM_TD1	PD3		PD3	PA3				Embedded Trace Module ETM data 1.
ETM_TD2	PD4		PD4	PA4				Embedded Trace Module ETM data 2.
ETM_TD3	PD5		PD5	PA5				Embedded Trace Module ETM data 3.
GPIO_EM4WU0	PA0							Pin can be used to wake the system up from EM4
GPIO_EM4WU2	PC9							Pin can be used to wake the system up from EM4
GPIO_EM4WU3	PF1							Pin can be used to wake the system up from EM4
GPIO_EM4WU4	PF2							Pin can be used to wake the system up from EM4
GPIO_EM4WU5	PE13							Pin can be used to wake the system up from EM4
HFX TAL_N	PB14							High Frequency Crystal negative pin. Also used as external optional clock input pin.
HFX TAL_P	PB13							High Frequency Crystal positive pin.
I2C0_SCL	PA1	PD7	PC7		PC1	PF1	PE13	I2C0 Serial Clock Line input / output.

BGA112 Pin# and Name		Pin Alternate Functionality / Description				
Pin #	Pin Name	Analog	EBI	Timers	Communication	Other
A3	PE12		EBI_AD04 #0/1/2	TIM1_CC2 #1	US0_RX #3 US0_CLK #0 I2C0_SDA #6	CMU_CLK1 #2 LES_ALTEX6 #0
A4	PE9		EBI_AD01 #0/1/2	PCNT2_S1IN #1		
A5	PD10		EBI_CS1 #0/1/2			
A6	PF7		EBI_BL1 #0/1/2	TIM0_CC1 #2	U0_RX #0	
A7	PF5		EBI_REn #0/2	TIM0_CDTI2 #2/5	USB_VBUSEN #0	PRS_CH2 #1
A8	PF12				USB_ID	
A9	PE4		EBI_A11 #0/1/2		US0_CS #1	
A10	PF10				U1_TX #1 USB_DM	
A11	PF11				U1_RX #1 USB_DP	
B1	PA15		EBI_AD08 #0/1/2	TIM3_CC2 #0		
B2	PE13		EBI_AD05 #0/1/2		US0_TX #3 US0_CS #0 I2C0_SCL #6	LES_ALTEX7 #0 ACMP0_O #0 GPIO_EM4WU5
B3	PE11		EBI_AD03 #0/1/2	TIM1_CC1 #1	US0_RX #0	LES_ALTEX5 #0 BOOT_RX
B4	PE8		EBI_AD00 #0/1/2	PCNT2_S0IN #1		PRS_CH3 #1
B5	PD11		EBI_CS2 #0/1/2			
B6	PF8		EBI_WEn #1	TIM0_CC2 #2		ETM_TCLK #1
B7	PF6		EBI_BL0 #0/1/2	TIM0_CC0 #2	U0_TX #0	
B8	USB_VBUS	USB 5.0 V VBUS input.				
B9	PE5		EBI_A12 #0/1/2		US0_CLK #1	
B10	USB_VREGI					
B11	USB_VREGO					
C1	PA1		EBI_AD10 #0/1/2	TIM0_CC1 #0/1	I2C0_SCL #0	CMU_CLK1 #0 PRS_CH1 #0
C2	PA0		EBI_AD09 #0/1/2	TIM0_CC0 #0/1/4	LEU0_RX #4 I2C0_SDA #0	PRS_CH0 #0 GPIO_EM4WU0
C3	PE10		EBI_AD02 #0/1/2	TIM1_CC0 #1	US0_TX #0	BOOT_TX
C4	PD13					ETM_TD1 #1
C5	PD12		EBI_CS3 #0/1/2			
C6	PF9		EBI_REn #1			ETM_TD0 #1
C7	VSS	Ground.				
C8	PF2		EBI_ARDY #0/1/2	TIM0_CC2 #5	LEU0_TX #4	ACMP1_O #0 DBG_SWO #0 GPIO_EM4WU4
C9	PE6		EBI_A13 #0/1/2		US0_RX #1	
C10	PC10	ACMP1_CH2	EBI_A10 #1/2	TIM2_CC2 #2	US0_RX #2	LES_CH10 #0

QFN64 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
2	PA1	LCD_SEG14	TIM0_CC1 #0/1	I2C0_SCL #0	CMU_CLK1 #0 PRS_CH1 #0
3	PA2	LCD_SEG15	TIM0_CC2 #0/1		CMU_CLK0 #0 ETM_TD0 #3
4	PA3	LCD_SEG16	TIM0_CDTI0 #0		LES_ALTEX2 #0 ETM_TD1 #3
5	PA4	LCD_SEG17	TIM0_CDTI1 #0		LES_ALTEX3 #0 ETM_TD2 #3
6	PA5	LCD_SEG18	TIM0_CDTI2 #0	LEU1_TX #1	LES_ALTEX4 #0 ETM_TD3 #3
7	PA6	LCD_SEG19		LEU1_RX #1	ETM_TCLK #3 GPIO_EM4WU1
8	IOVDD_0	Digital IO power supply 0.			
9	PB3	LCD_SEG20/ LCD_COM4	PCNT1_S0IN #1	US2_TX #1	
10	PB4	LCD_SEG21/ LCD_COM5	PCNT1_S1IN #1	US2_RX #1	
11	PB5	LCD_SEG22/ LCD_COM6		US2_CLK #1	
12	PB6	LCD_SEG23/ LCD_COM7		US2_CS #1	
13	PC4	ACMP0_CH4 OPAMP_P0	TIM0_CDTI2 #4 LE- TIM0_OUT0 #3 PCNT1_S0IN #0	US2_CLK #0 I2C1_SDA #0	LES_CH4 #0
14	PC5	ACMP0_CH5 OPAMP_N0	LETIM0_OUT1 #3 PCNT1_S1IN #0	US2_CS #0 I2C1_SCL #0	LES_CH5 #0
15	PB7	LFXTAL_P	TIM1_CC0 #3	US0_TX #4 US1_CLK #0	
16	PB8	LFXTAL_N	TIM1_CC1 #3	US0_RX #4 US1_CS #0	
17	PA12	LCD_BCAP_P	TIM2_CC0 #1		
18	PA13	LCD_BCAP_N	TIM2_CC1 #1		
19	PA14	LCD_BEXT	TIM2_CC2 #1		
20	RESETn	Reset input, active low. To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released.			
21	PB11	DAC0_OUT0 / OPAMP_OUT0	TIM1_CC2 #3 LE- TIM0_OUT0 #1	I2C1_SDA #1	
22	PB12	DAC0_OUT1 / OPAMP_OUT1	LETIM0_OUT1 #1	I2C1_SCL #1	
23	AVDD_1	Analog power supply 1.			
24	PB13	HFXTAL_P		US0_CLK #4/5 LEU0_TX #1	
25	PB14	HFXTAL_N		US0_CS #4/5 LEU0_RX #1	
26	IOVDD_3	Digital IO power supply 3.			

LQFP100 Pin# and Name		Pin Alternate Functionality / Description				
Pin #	Pin Name	Analog	EBI	Timers	Communication	Other
24	PB7	LFXTAL_P		TIM1_CC0 #3	US0_TX #4 US1_CLK #0	
25	PB8	LFXTAL_N		TIM1_CC1 #3	US0_RX #4 US1_CS #0	
26	PA7	LCD_SEG35	EBI_CSTFT #0/1/2			
27	PA8	LCD_SEG36	EBI_DCLK #0/1/2	TIM2_CC0 #0		
28	PA9	LCD_SEG37	EBI_DTEN #0/1/2	TIM2_CC1 #0		
29	PA10	LCD_SEG38	EBI_VSNC #0/1/2	TIM2_CC2 #0		
30	PA11	LCD_SEG39	EBI_HSNC #0/1/2			
31	IOVDD_2	Digital IO power supply 2.				
32	VSS	Ground.				
33	PA12	LCD_BCAP_P	EBI_A00 #0/1/2	TIM2_CC0 #1		
34	PA13	LCD_BCAP_N	EBI_A01 #0/1/2	TIM2_CC1 #1		
35	PA14	LCD_BEXT	EBI_A02 #0/1/2	TIM2_CC2 #1		
36	RESETn	Reset input, active low. To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released.				
37	PB9		EBI_A03 #0/1/2		U1_TX #2	
38	PB10		EBI_A04 #0/1/2		U1_RX #2	
39	PB11	DAC0_OUT0 / OPAMP_OUT0		TIM1_CC2 #3 LE- TIM0_OUT0 #1	I2C1_SDA #1	
40	PB12	DAC0_OUT1 / OPAMP_OUT1		LETIM0_OUT1 #1	I2C1_SCL #1	
41	AVDD_1	Analog power supply 1.				
42	PB13	HFXTAL_P			US0_CLK #4/5 LEU0_TX #1	
43	PB14	HFXTAL_N			US0_CS #4/5 LEU0_RX #1	
44	IOVDD_3	Digital IO power supply 3.				
45	AVDD_0	Analog power supply 0.				
46	PD0	ADC0_CH0 DAC0_OUT0ALT #4/ OPAMP_OUT0ALT OPAMP_OUT2 #1		PCNT2_S0IN #0	US1_TX #1	
47	PD1	ADC0_CH1 DAC0_OUT1ALT #4/ OPAMP_OUT1ALT		TIM0_CC0 #3 PCNT2_S1IN #0	US1_RX #1	DBG_SWO #2
48	PD2	ADC0_CH2	EBI_A27 #0/1/2	TIM0_CC1 #3	USB_DMPU #0 US1_CLK #1	DBG_SWO #3
49	PD3	ADC0_CH3 OPAMP_N2		TIM0_CC2 #3	US1_CS #1	ETM_TD1 #0/2

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
ADC0_CH7	PD7							Analog to digital converter ADC0, input channel number 7.
BOOT_RX	PE11							Bootloader RX.
BOOT_TX	PE10							Bootloader TX.
BU_STAT	PE3							Backup Power Domain status, whether or not the system is in backup mode
BU_VIN	PD8							Battery input for Backup Power Domain
BU_VOUT	PE2							Power output for Backup Power Domain
CMU_CLK0	PA2	PC12	PD7					Clock Management Unit, clock output number 0.
CMU_CLK1	PA1	PD8	PE12					Clock Management Unit, clock output number 1.
OPAMP_N0	PC5							Operational Amplifier 0 external negative input.
OPAMP_N1	PD7							Operational Amplifier 1 external negative input.
OPAMP_N2	PD3							Operational Amplifier 2 external negative input.
DAC0_OUT0 / OPAMP_OUT0	PB11							Digital to Analog Converter DAC0_OUT0 /OPAMP output channel number 0.
DAC0_OUT0ALT / OPAMP_OUT0A LT	PC0	PC1	PC2	PC3	PD0			Digital to Analog Converter DAC0_OUT0ALT / OPAMP alternative output for channel 0.
DAC0_OUT1 / OPAMP_OUT1	PB12							Digital to Analog Converter DAC0_OUT1 /OPAMP output channel number 1.
DAC0_OUT1ALT / OPAMP_OUT1A LT	PC12	PC13	PC14	PC15	PD1			Digital to Analog Converter DAC0_OUT1ALT / OPAMP alternative output for channel 1.
OPAMP_OUT2	PD5	PD0						Operational Amplifier 2 output.
OPAMP_P0	PC4							Operational Amplifier 0 external positive input.
OPAMP_P1	PD6							Operational Amplifier 1 external positive input.
OPAMP_P2	PD4							Operational Amplifier 2 external positive input.
DBG_SWCLK	PF0	PF0	PF0	PF0				Debug-interface Serial Wire clock input. Note that this function is enabled to pin out of reset, and has a built-in pull down.
DBG_SWDIO	PF1	PF1	PF1	PF1				Debug-interface Serial Wire data input / output. Note that this function is enabled to pin out of reset, and has a built-in pull up.
DBG_SWO	PF2		PD1	PD2				Debug-interface Serial Wire viewer Output. Note that this function is not enabled after reset, and must be enabled by software to be used.
EBI_A00	PA12	PA12	PA12					External Bus Interface (EBI) address output pin 00.
EBI_A01	PA13	PA13	PA13					External Bus Interface (EBI) address output pin 01.
EBI_A02	PA14	PA14	PA14					External Bus Interface (EBI) address output pin 02.
EBI_A03	PB9	PB9	PB9					External Bus Interface (EBI) address output pin 03.

Water Pads and Coordinates				Pad Alternative Functionality / Description				
Pad #	Pad Name	X (µm)	Y (µm)	Analog	EBI	Timers	Communica- tion	Other
25	PC3	-2065.0	-1322.6	ACMP0_CH3 DAC0_OUT0ALT T #3/ OPAMP_OUT0 ALT	EBI_NANDREn #0/1/2	TIM0_CDTI1 #4	US2_RX #0	LES_CH3 #0
26	PC4	-2065.0	-1484.3	ACMP0_CH4 OPAMP_P0	EBI_A26 #0/1/2	TIM0_CDTI2 #4 LETIM0_OUT0 #3 PCNT1_S0IN #0	US2_CLK #0 I2C1_SDA #0	LES_CH4 #0
27	PC5	-2065.0	-1586.5	ACMP0_CH5 OPAMP_N0	EBI_NANDWEEn #0/1/2	LETIM0_OUT1 #3 PCNT1_S1IN #0	US2_CS #0 I2C1_SCL #0	LES_CH5 #0
28	PB7	-2065.0	-1708.6	LFXTAL_P		TIM1_CC0 #3	US0_TX #4 US1_CLK #0	
29	PB8	-2065.0	-1830.6	LFXTAL_N		TIM1_CC1 #3	US0_RX #4 US1_CS #0	
30	PA7	-1832.5	-2065.0	LCD_SEG35	EBI_CSTFT #0/1/2			
31	PA8	-1695.5	-2065.0	LCD_SEG36	EBI_DCLK #0/1/2	TIM2_CC0 #0		
32	PA9	-1558.5	-2065.0	LCD_SEG37	EBI_DTEN #0/1/2	TIM2_CC1 #0		
33	PA10	-1421.5	-2065.0	LCD_SEG38	EBI_VSNC #0/1/2	TIM2_CC2 #0		
34	PA11	-1284.5	-2065.0	LCD_SEG39	EBI_HSNC #0/1/2			
35	IOVDD_2	-1147.5	-2065.0	Digital IO power supply 2.				
36	IOVSS_2	-1027.4	-2065.0	Digital IO ground 2.				
37	PA12	-907.2	-2065.0	LCD_BCAP_P	EBI_A00 #0/1/2	TIM2_CC0 #1		
38	PA13	-780.6	-2065.0	LCD_BCAP_N	EBI_A01 #0/1/2	TIM2_CC1 #1		
39	PA14	-654.0	-2065.0	LCD_BEXT	EBI_A02 #0/1/2	TIM2_CC2 #1		
40	RESETn	-527.4	-2065.0	Reset input, active low. To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released.				
41	PB9	-401.0	-2065.0		EBI_A03 #0/1/2		U1_TX #2	
42	PB10	-274.5	-2065.0		EBI_A04 #0/1/2		U1_RX #2	
43	PB11	260.7	-2065.0	DAC0_OUT0 / OPAMP_OUT0		TIM1_CC2 #3 LETIM0_OUT0 #1	I2C1_SDA #1	
44	PB12	366.0	-2065.0	DAC0_OUT1 / OPAMP_OUT1		LETIM0_OUT1 #1	I2C1_SCL #1	
45	AVSS_2	464.8	-2065.0	Analog ground 2.				
46	AVDD_2	560.5	-2065.0	Analog power supply 2.				

Alternate	LOCATION							Description
Functionality	0	1	2	3	4	5	6	
LCD_SEG18	PA5							LCD segment line 18. Segments 16, 17, 18 and 19 are controlled by SEGEN4.
LCD_SEG20/ LCD_COM4	PB3							LCD segment line 20. Segments 20, 21, 22 and 23 are controlled by SEGEN5. This pin may also be used as LCD COM line 4
LCD_SEG21/ LCD_COM5	PB4							LCD segment line 21. Segments 20, 21, 22 and 23 are controlled by SEGEN5. This pin may also be used as LCD COM line 5
LCD_SEG22/ LCD_COM6	PB5							LCD segment line 22. Segments 20, 21, 22 and 23 are controlled by SEGEN5. This pin may also be used as LCD COM line 6
LCD_SEG23/ LCD_COM7	PB6							LCD segment line 23. Segments 20, 21, 22 and 23 are controlled by SEGEN5. This pin may also be used as LCD COM line 7
LES_ALTEX0	PD6							LESENSE alternate exite output 0.
LES_ALTEX1	PD7							LESENSE alternate exite output 1.
LES_ALTEX2	PA3							LESENSE alternate exite output 2.
LES_ALTEX3	PA4							LESENSE alternate exite output 3.
LES_ALTEX4	PA5							LESENSE alternate exite output 4.
LES_ALTEX5	PE11							LESENSE alternate exite output 5.
LES_ALTEX6	PE12							LESENSE alternate exite output 6.
LES_ALTEX7	PE13							LESENSE alternate exite output 7.
LES_CH4	PC4							LESENSE channel 4.
LES_CH5	PC5							LESENSE channel 5.
LES_CH6	PC6							LESENSE channel 6.
LES_CH7	PC7							LESENSE channel 7.
LETIM0_OUT0	PD6	PB11	PF0	PC4				Low Energy Timer LETIM0, output channel 0.
LETIM0_OUT1	PD7		PF1	PC5				Low Energy Timer LETIM0, output channel 1.
LEU0_RX	PD5	PB14	PE15	PF1	PA0			LEUART0 Receive input.
LEU0_TX	PD4	PB13	PE14	PF0	PF2			LEUART0 Transmit output. Also used as receive input in half duplex communication.
LEU1_RX	PC7							LEUART1 Receive input.
LEU1_TX	PC6	PA5						LEUART1 Transmit output. Also used as receive input in half duplex communication.
LFXTAL_N	PB8							Low Frequency Crystal (typically 32.768 kHz) negative pin. Also used as an optional external clock input pin.
LFXTAL_P	PB7							Low Frequency Crystal (typically 32.768 kHz) positive pin.
PCNT0_S0IN				PD6				Pulse Counter PCNT0 input number 0.
PCNT0_S1IN				PD7				Pulse Counter PCNT0 input number 1.
PCNT1_S0IN	PC4	PB3						Pulse Counter PCNT1 input number 0.

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
EBI_AD09	PA0	PA0	PA0					External Bus Interface (EBI) address and data input / output pin 09.
EBI_AD10	PA1	PA1	PA1					External Bus Interface (EBI) address and data input / output pin 10.
EBI_AD11	PA2	PA2	PA2					External Bus Interface (EBI) address and data input / output pin 11.
EBI_AD12	PA3	PA3	PA3					External Bus Interface (EBI) address and data input / output pin 12.
EBI_AD13	PA4	PA4	PA4					External Bus Interface (EBI) address and data input / output pin 13.
EBI_AD14	PA5	PA5	PA5					External Bus Interface (EBI) address and data input / output pin 14.
EBI_AD15	PA6	PA6	PA6					External Bus Interface (EBI) address and data input / output pin 15.
EBI_ALE	PF3	PC11	PC11					External Bus Interface (EBI) Address Latch Enable output.
EBI_ARDY	PF2	PF2	PF2					External Bus Interface (EBI) Hardware Ready Control input.
EBI_BL0	PF6	PF6	PF6					External Bus Interface (EBI) Byte Lane/Enable pin 0.
EBI_BL1	PF7	PF7	PF7					External Bus Interface (EBI) Byte Lane/Enable pin 1.
EBI_CS0	PD9	PD9	PD9					External Bus Interface (EBI) Chip Select output 0.
EBI_CS1	PD10	PD10	PD10					External Bus Interface (EBI) Chip Select output 1.
EBI_CS2	PD11	PD11	PD11					External Bus Interface (EBI) Chip Select output 2.
EBI_CS3	PD12	PD12	PD12					External Bus Interface (EBI) Chip Select output 3.
EBI_CSTFT	PA7	PA7	PA7					External Bus Interface (EBI) Chip Select output TFT.
EBI_DCLK	PA8	PA8	PA8					External Bus Interface (EBI) TFT Dot Clock pin.
EBI_DTEN	PA9	PA9	PA9					External Bus Interface (EBI) TFT Data Enable pin.
EBI_HSNC	PA11	PA11	PA11					External Bus Interface (EBI) TFT Horizontal Synchronization pin.
EBI_NANDREn	PC3	PC3	PC3					External Bus Interface (EBI) NAND Read Enable output.
EBI_NANDWEn	PC5	PC5	PC5					External Bus Interface (EBI) NAND Write Enable output.
EBI_REn	PF5	PF9	PF5					External Bus Interface (EBI) Read Enable output.
EBI_VSNC	PA10	PA10	PA10					External Bus Interface (EBI) TFT Vertical Synchronization pin.
EBI_WEn	PF4	PF8	PF4					External Bus Interface (EBI) Write Enable output.
ETM_TCLK	PD7	PF8	PC6	PA6				Embedded Trace Module ETM clock .
ETM_TD0	PD6	PF9	PC7	PA2				Embedded Trace Module ETM data 0.
ETM_TD1	PD3	PD13	PD3	PA3				Embedded Trace Module ETM data 1.

Alternate	LOCATION							Description
Functionality	0	1	2	3	4	5	6	
US2_CS	PC5	PB6						USART2 chip select input / output.
US2_RX	PC3	PB4						USART2 Asynchronous Receive. USART2 Synchronous mode Master Input / Slave Output (MISO).
US2_TX	PC2	PB3						USART2 Asynchronous Transmit. Also used as receive input in half duplex communication. USART2 Synchronous mode Master Output / Slave Input (MOSI).
USB_DM	PF10							USB D- pin.
USB_DMPU	PD2							USB D- Pullup control.
USB_DP	PF11							USB D+ pin.
USB_ID	PF12							USB ID pin. Used in OTG mode.
USB_VBUS	USB_VBUS							USB 5 V VBUS input.
USB_VBUSEN	PF5							USB 5 V VBUS enable.
USB_VREGI	USB_VREGI							USB Input to internal 3.3 V regulator
USB_VREGO	USB_VREGO							USB Decoupling for internal 3.3 V USB regulator and regulator output

5.22.3 GPIO Pinout Overview

The specific GPIO pins available in EFM32LG995 is shown in the following table. Each GPIO port is organized as 16-bit ports indicated by letters A through F, and the individual pin on this port is indicated by a number from 15 down to 0.

Table 5.66. GPIO Pinout

Port	Pin 15	Pin 14	Pin 13	Pin 12	Pin 11	Pin 10	Pin 9	Pin 8	Pin 7	Pin 6	Pin 5	Pin 4	Pin 3	Pin 2	Pin 1	Pin 0
Port A	PA15	PA14	PA13	PA12	PA11	PA10	PA9	PA8	PA7	PA6	PA5	PA4	PA3	PA2	PA1	PA0
Port B	PB15	PB14	PB13	PB12	PB11	PB10	PB9	PB8	PB7	PB6	PB5	PB4	PB3	PB2	PB1	PB0
Port C	PC15	PC14	PC13	PC12	PC11	PC10	PC9	PC8	PC7	PC6	PC5	PC4	PC3	PC2	PC1	PC0
Port D	PD15	PD14	PD13	PD12	PD11	PD10	PD9	PD8	PD7	PD6	PD5	PD4	PD3	PD2	PD1	PD0
Port E	PE15	PE14	PE13	PE12	PE11	PE10	PE9	PE8	PE7	PE6	PE5	PE4	PE3	PE2	PE1	PE0
Port F	—	—	—	PF12	PF11	PF10	PF9	PF8	PF7	PF6	PF5	PF4	PF3	PF2	PF1	PF0

8. CSP81 Package Specifications

8.1 CSP81 Package Dimensions

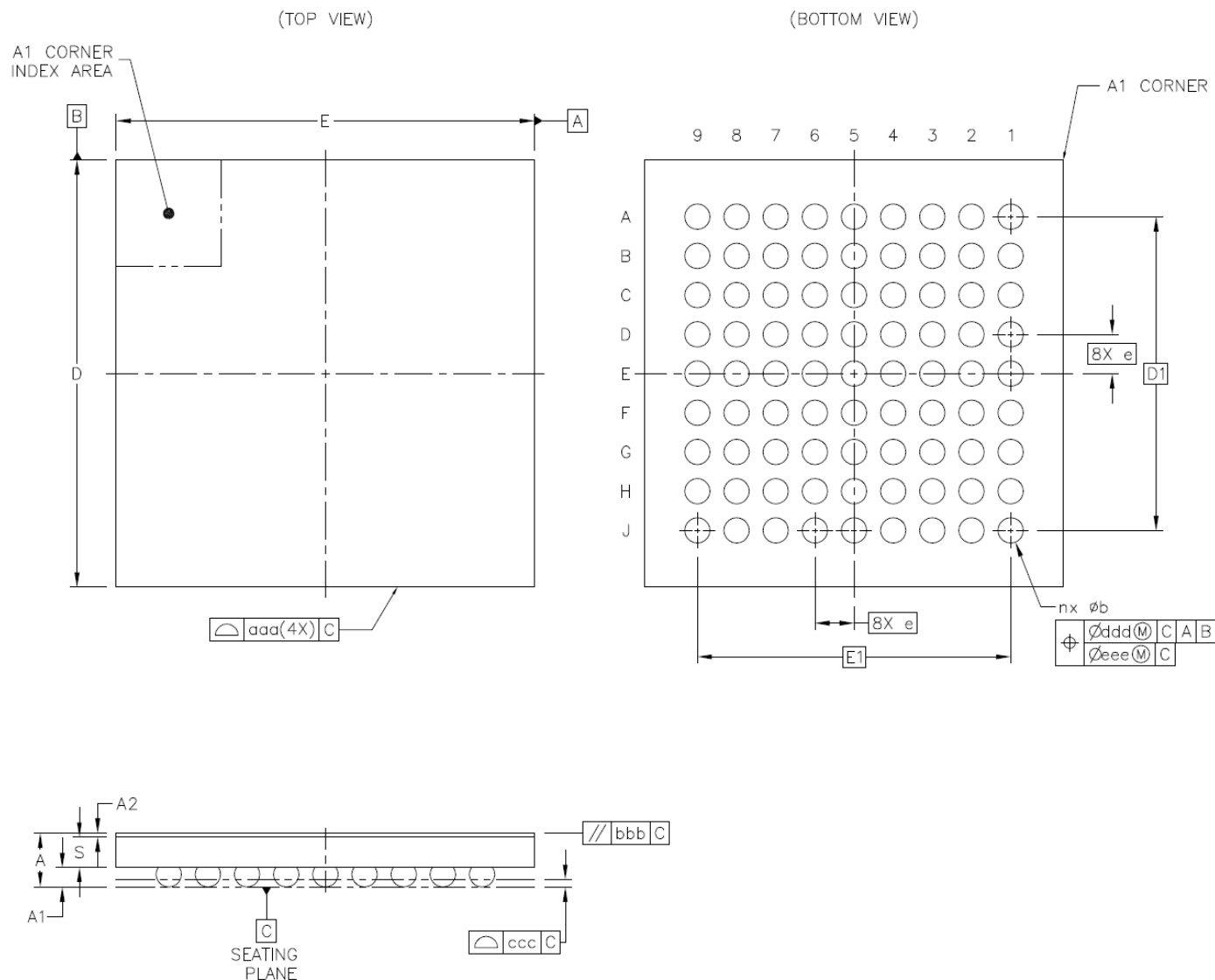


Figure 8.1. CSP81

Note:

1. All dimensions shown are in millimeters (mm) unless otherwise noted.
2. Dimensioning and Tolerancing per ANSI Y14.5M-1994.
3. Primary datum "C" and seating plane are defined by the spherical crowns of the solder balls.
4. Dimension "b" is measured at the maximum solder bump diameter, parallel to primary datum "C".
5. Recommended card reflow profile is per the JEDEC/IPC J-STD-020C specification for Small Body Components.

Table 8.1. CSP81 (Dimensions in mm)

Symbol	Min	Nom	Max
A	0.491	0.55	0.609
A1	0.17	—	0.23

12. Wafer Specifications

12.1 Bonding Instructions

All pads should be bonded out, with the exception of the pads labeled “NC” and listed as “Do not connect” in Padout. Gold bond wires are recommended for these devices.

All three voltage regulator output decouple pads (DEC_0, DEC_1, DEC_2) must be bonded out and electrically connected on the PCB. In the packaged devices, these three pads are all bonded to a single DECOUPLE pin.

If the USB feature of EFM32LG900 will be used, all of the USB pads must be bonded out, and

- both USB_VREGO_0 and USB_VREGO_1 must be bonded out and electrically connected on the PCB. In the packaged devices, these two pads are both bonded to a single USB_VREGO pin.
- both USB_VREGI_0 and USB_VREGI_1 must be bonded out and electrically connected on the PCB. In the packaged devices, these two pads are both bonded to a single USB_VREGI pin.

12.2 Wafer Description

Table 12.1. Wafer and Die Information

Parameter	Value
Device Family	EFM32LG (Leopard Gecko)
Wafer Diameter	8 in
Die Dimensions (Outer edge of seal ring)	4230 μm $\times$ 4230 μm
Wafer Thickness (No backgrind)	725 μm $\pm$ 15 μm (28.54 mil $\pm$ 1 mil)
Wafer Identification	Notch
Scribe Street Width	80 μm $\times$ 160 μm
Die Per Wafer ¹	Contact sales for information
Passivation	Standard
Wafer Packaging Detail	Wafer Jar
Bond Pad Dimensions	65 μm (parallel to die edge) $\times$ 66 μm
Bond Pad Pitch Minimum	76 μm
Maximum Processing Temperature	250°C
Electronic Die Map Format	.txt
Note: 1. This is the Expected Known Good Die yielded per wafer and represents the batch order quantity (one wafer).	

12.2.1 Environmental

Bare silicon die are susceptible to mechanical damage and may be sensitive to light. When bare die must be used in an environment exposed to light, it may be necessary to cover the top and sides with an opaque material.

For additional Quality and Environmental information, please see: <http://www.silabs.com/support/quality/pages/default.aspx>.